

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Harry A. ATWATER, Jr. et al.

Title:

WAFER BONDED VIRTUAL SUBSTRATE AND METHOD

FOR FORMING THE SAME

Appl. No.:

10/761,918

Filing Date:

1/20/2004

Examiner:

Duy-Vu DEO

Art Unit:

1765

Confirmation

4108

Number:

TERMINAL DISCLAIMER 2

Mail Box AF Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Your Petitioner, California Institute of Technology, having its principal place of business at 1200 East California Boulevard, Pasadena, California, represents that it is the owner of the entire right, title, and interest in and to U.S. Patent Application No. 10/761,918, filed 1/20/2004, which is a continuation-in-part of U.S. Patent Application No. 10/125,133, filed 4/17/2002, by virtue of an Assignment filed and recorded on 7/15/2004, on Reel/Frame 015566/0827, in the United States Patent and Trademark Office, a copy of which is attached hereto as APPENDIX A.

Further, your Petitioner represents that it is the owner of U.S. Patent Application No. 11/004,948, filed 12/7/2004, which is a continuation of U.S. Patent Application No. 10/761,918, filed 1/20/2004, which is a continuation-in-part of U.S. Patent Application No. 10/125,133 filed 4/17/2002, by virtue of an Assignment filed and recorded 19/18/1918

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on 7/15/2004, on Reel/Frame 015566/0827, in the United States Patent and Trademark Office, a copy of which is attached hereto as APPENDIX A.

Your Petitioner, California Institute of Technology, hereby disclaims the terminal part of the term of any patent granted on U.S. Patent Application 10/761,918 which would extend beyond the full statutory term, as shortened by any terminal disclaimer, of any patent granted on U.S. Patent Application 11/004,948, and hereby agrees that any patent so granted on U.S. Patent Application 10/761,918 shall be enforceable only for and during such period that the legal title to any patent granted on U.S. Patent Application 11/004,948 shall be the same as the legal title to any patent granted on U.S. Patent Application 10/761,918, this agreement to run with any patent granted on U.S. Patent Application 10/761,918 and to be binding upon the grantee, its successors or assigns.

In making the above disclaimer, Petitioner does not disclaim any terminal part of any patent granted on U.S. Patent Application 10/761,918, prior to the full statutory term of any patent granted on U.S. Patent Application 11/004,948 as defined in 35 U.S.C. §§154-156 and 173, in the event that any patent granted on U.S. Patent Application 11/004,948 expires for failure to pay a maintenance fee, is held unenforceable or is found invalid in a final judgment by a court of competent jurisdiction, is statutorily disclaimed in whole or terminally disclaimed under 37 CFR §1.321(a), has all claims canceled by a reexamination certificate or as a result of an interference proceeding, or is otherwise not deemed to provide the rights conveyed by 35 USC §154, prior to the full statutory term of any patent granted on U.S. Patent Application 11/004,948 as defined in 35 USC §§154-156 and 173, except for the separation of legal title stated above. Further, Petitioner does not disclaim any terminal part of a patent granted on U.S. Patent Application 10/761,918 that would extend beyond the present termination of any patent granted on U.S. Patent Application 11/004,948, in the event that such present term is extended by virtue of compliance with the conditions for term extension of any present or future patent term extension provisions of the patent law, including but not limited to 35 U.S.C. §§155, 155A or 156, and without waiving Petitioner's right to extend the term of a patent granted on U.S. Patent Application 10/761,918 to the extent provided by law.

The undersigned, being the Attorney of Record for U.S. Patent Application 10/761,918, and duly authorized to act on behalf of Petitioner, certifies that he has reviewed the Assignments attached as APPENDIX A, and to the best of his knowledge and belief, legal title to U.S. Patent Application 10/761,918 and any patent granted on U.S. Patent Application 11/004,948 rests with Petitioners, California Institute of Technology. The undersigned declares that all statements made herein of his own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001, Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the above-identified application or any patent issuing therefrom.

Respectfully submitted,

Stephen B. Maebius

Attorney for Applicant Registration No. 35,264

Date

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FOLEY & LARDNER LLP

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FORM PTO-1595 (Modified) (Rev. 03-01) OMB No. 0651-0027 (exp.5/31/2002) POB/REV03 Tab settings	RM COVER SHEL.	U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office
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To the Director of the United States Pagent and Trademark Office	e: Please record the a	<u> </u>
Name of conveying party(ies)	2. Name and addr	ess of receiving party(ies):
Harry A. Atwater, Jr. Anna Fontcuberta i Morral James M. Zahler	Name: Californ	nia Institute of Technology
James W. Zamer	Internal Address	3:
Additional names(s) of conveying party(ies)		
3. Nature of conveyance:		
☑ Assignment ☐ Merger	Street Address:	1200 East California Boulevard
☐ Security Agreement ☐ Change of Name		
☐ Other	City: Pasadena	State: <u>CA</u> ZIP: <u>91125</u>
Execution Date: 04/21/04; 04/19/04; 04/19/04	Additional name(s) &	& address(es) attached? ☐ Yes 🛛 No
4. Application number(s) or patent numbers(s):		
If this document is being filed together with a new application,		
A. Patent Application No.(s)	B. Patent I	No.(s)
10/761,918		
·		
Additional numbers attac	hed? ∐ Yes ⊠	No
Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of	applications and patents involved:
Name: Daniel L. Dawes	7. Total fee (37 CF	R 3.41):\$ 40.00
Internal Address: MYERS DAWES ANDRAS &	⊠ Enclosed - A	Any excess or insufficiency should be
SHERMAN LLP		lebited to deposit account 01-1960
	☐ Authorized to	o be charged to deposit account
Street Address: 19900 MacArthur Boulevard, Suite 1150	8. Deposit account	number:
City: Irvine State: CA ZIP: 92612	(Attach duplicate co	py of this page if paying by deposit account)
	SE THIS SPACE	7
Statement and signature. To the best of my knowledge and belief, the foregoing information.	lion is true and com	ect and any attached copy is a true copy
of the original document.	11/1/	,,
Daniel L. Dawes	It la	July 14, 2004
Name of Person Signing	algoature	Date Date
Total number of pages including cover she	et, attachments, and	document:

Mail documents to be recorded with required cover sheet information to:

Mail Stop Assignment Recordation Services

Director of the United States Patent and Trademark Office, P.O. Box 1450, Alexandria, VA 22313-1450

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ASSIGNMENT

CIT Case No. 3453-2

and which is found in

For good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S),

Harry A. Atwater Jr.

hereby sells, assigns and transfers to ASSIGNEE, California Institute of Technology, having its statewide administrative offices located at 1200 East California Boulevard, Pasadena, California 91125, and the successors, assigns and legal representatives of the ASSIGNEE, all of its rights, title and interest for the United States and its territorial possessions and in all foreign countries in and to, any and all improvements which are disclosed in the invention entitled:

A Water Bonded Virtual Substrate and Method for Forming the Same

			_		
(a)	U.S. provisional application filed herewith and listing the above named persons as inventors				
(p)	U.S. patent application filed herewith and listing the above named persons as inventors				
	U.S. application serial no.				
(d)	U.S. Patent No.:		, lasued		
and any legal equivalent thereof in a foreign country, including the right to claim priority and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, continuation-in-part, extension, conversion to 35 USC 111(a) or substitute thereof, and any reissue, reexamination or extension of said Letters Patent and all under all international Conventions for the Protection of Industrial Property;					
ASSIGNOR(S) hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment,					
ASSIGNOR(S) further coverants that the ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation, or proceeding relating thereto and will promptly execute and deliver to ASSIGNEE or its legal representative any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue or enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof. An attorney of record is authorized and requested by the execution of this assignment to insert into this assignment the filing date and serial number of said application when officially known.					
AND the <u>ASSIGNOR(S)</u> requests the Commissioner of Patents and Trademarks to issue said Letters Patent of the United States and any reliasue or extension thereof to the ASSIGNEE, California Institute of Technology.					
executed	this	Sig	gnature of Invent	or(s)	
19th d	lay of April 2000	- / H	MANUAL ST.	Aprilo	

ASSIGNMENT

CIT Case No. 3453-CIP

For good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S),

James M. Zahler

hereby sells, assigns and transfers to ASSIGNEE, California Institute of Technology, having its statewide administrative offices located at 1200 East California Boulevard, Pasadena, California 91125, and the successors, assigns and legal representatives of the ASSIGNEE, all of its rights, title and interest for the United States and its territorial possessions and in all foreign countries in and to, any and all improvements which are disclosed in the invention entitled:

A Wafer Bonded Virtual Substrate and Method for Forming the Same

and which	n is found in			
(a)	U.S. provisional application filed herewith and listing the above named persons as inventors			
(b)	U.S. patent application filed herewith and listing the above	e named persons as	inventors	
(c) <u>X</u>	U.S. application serial no. 10/761,918	, filed on	01/20/2004	
(d)	U.S. Patent No.:	, issued		
and any legal equivalent thereof in a foreign country, including the right to claim priority and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, continuation-in-part, extension, conversion to 35 USC 111(a) or substitute thereof, and any reissue, reexamination or extension of said Letters Patent and all under all International Conventions for the Protection of Industrial Property;				
ASSIGNOR(S) hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;				
ASSIGNOR(S) further covenants that the ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation, or proceeding relating thereto and will promptly execute and deliver to ASSIGNEE or its legal representative any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue or enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof. An attorney of record is authorized and requested by the execution of this assignment to insert into this assignment the filing date and serial number of said application when officially known.				
AND the <u>ASSIGNOR(S)</u> requests the Commissioner of Patents and Trademarks to issue said Letters Patent of the United States and any reissue or extension thereof to the ASSIGNEE, California Institute of Technology.				
executed	this S	ignature of Inventor(s	s)	
215T	day of <u>APRIL</u> , 20 <u>04</u>	ames M. Zahler		

ASSIGNMENT

CIT Case No. 3453-CIP

For good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S),

Anna Fontcuberta i Morral

hereby sells, assigns and transfers to ASSIGNEE, California Institute of Technology, having its statewide administrative offices located at 1200 East California Boulevard, Pasadena, California 91125, and the successors, assigns and legal representatives of the ASSIGNEE, all of its rights, title and interest for the United States and its territorial possessions and in all foreign countries in and to, any and all improvements which are disclosed in the invention entitled:

A Wafer Bonded Virtual Substrate and Method for Forming the Same

and which is found in				
(a) U.S. provisional application filed herewith and listing th	e above named persons as inventors			
(b) U.S. patent application filed herewith and listing the ab	ove named persons as inventors			
(c) X U.S. application serial no. 10/761,918	, filed on01/20/2004			
(d) U.S. Patent No.:	, issued			
and any legal equivalent thereof in a foreign country, including the obtained for said invention by the above application or a conversion to 35 USC 111(a) or substitute thereof, and any reissall under all International Conventions for the Protection of Indus	ny continuation, division, continuation-in-part, extension, sue, reexamination or extension of said Letters Patent and			
ASSIGNOR(S) hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;				
ASSIGNOR(S) further covenants that the ASSIGNEE will, upor and documents relating to said invention and said Letters Patent ASSIGNOR and will testify as to the same in any interference, execute and deliver to ASSIGNEE or its legal representative any for, obtain, maintain, issue or enforce said application, said inverwhich may be necessary or desirable to carry out the purposes to the execution of this assignment to insert into this assignment officially known.	and legal equivalents as may be known and accessible to litigation, or proceeding relating thereto and will promptly and all papers, instruments or affidavits required to apply ntion and said Letters Patent and said equivalents thereof hereof. An attorney of record is authorized and requested			
AND the <u>ASSIGNOR(S)</u> requests the Commissioner of Patents and Trademarks to issue said Letters Patent of the United States and any reissue or extension thereof to the ASSIGNEE, California Institute of Technology.				
executed this	Signature of Inventor(s)			
19th day of april , 2004	Anna Fontcuberta i Morral			